

**Amendments to the Abstract:**

Please replace the paragraph beginning on page 24 with the following:

~~In the present invention, a device~~ Techniques for inspecting semiconductor devices. An inspection condition using chip matrix data and chip size data is set.[[,]] ~~which inspects~~ The intricate circuit patterns of at least one semiconductor device is inspected with the inspection condition. In an embodiment of the present invention, inspection uses ~~using~~ images formed by the irradiation of white light, a laser light, or an electron beam[[,]]. ~~is equipped with a function that enables automatic setting of a plurality of parameters in the inspection device by using semiconductor device design data.~~ Data obtained from the inspection is used to generate a revised inspection condition. Semiconductor devices are inspected using the revised inspection condition. ~~This helps to improve the operation efficiency of inspection when the conditions required for inspection are set.~~